Technical Data Sheet

EtroX® I CM UHT natural

PI

Typical characteristics

- Good thermo-oxidative stability (use up to 450°C)
- high dimensional stability under heat
- Heat resistant
- Low creep tendency
- Low moisture absorption

Typical industries

- Electronics
- Semiconductor Back-End applications
- Semiconductor Wafer Handling
- Semiconductor High and low temperature
- Semiconductor Dicing
- Vehicle Construction
- Mechanical Engineering Industry

	Test method	Unit	Guideline value
General properties			
Density	DIN EN ISO 1183-1	g / cm^3	1,43
Water absorption	DIN EN ISO 62 (23°C / 24h)	%	0,06
Water absorption	DIN EN ISO 62 (23°C / 48h)	%	0,1
Water absorption	DIN EN ISO 62 (23°C / 3 Weeks)	%	0,4
Mechanical properties			
Elongation at break	DIN EN ISO 527	%	4
Tensile modulus of elasticity	DIN EN ISO 527	MPa	4800
Tensile strength	DIN EN ISO 527	MPa	142
Impact strength	DIN EN ISO 179	kJ / m^2	40
Notched impact strength	DIN EN ISO 179	kJ / m^2	3
Shore hardness	DIN EN ISO 868	scale D	90
Flexural Modulus	ASTM D790	ksi	750
Elastic modulus of compression	DIN EN ISO 604	MPa	4000
Thermal properties			
Glass transition temperature	ISO 11357-3	°C	270
Service temperature, short term (max.)	Average	°C	450

	Test method	Unit	Guideline value
Temp. of deflection under load, 1.80 MPa	ISO 75-1/-2	°C	265
Temp. of deflection under load, 0.45 MPa	ISO 75-1/-2	°C	304
Electrical properties			
Volume resistivity	DIN EN 62631-3-1	Ω * cm	$>10^{11}$
Dielectric constant @ 1MHz	DIN EN IEC 62631-2-1		3,3